



Click [here](#) for the 3D model.

Dimensions

Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	0.78mm +/-0.10mm
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	Cut Reel
Packaging Quantity	500

General Information

Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	560 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms